

Title (en)
HEAT PUMP DEVICE

Title (de)
WÄRMEPUMPENVORRICHTUNG

Title (fr)
DISPOSITIF DE POMPE À CHALEUR

Publication
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Application
EP 16799525 A 20160512

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Abstract (en)
A heat pump device of the present invention includes a first refrigeration circuit, a second refrigeration circuit, and a controller. The first refrigeration circuit includes a first compressor, a first condenser, a first throttle tool, and a first evaporator connected in a ring and lets a first refrigerant circulate. The second refrigeration circuit lets a second refrigerant circulate and exchanges heat with the first refrigeration circuit via the first evaporator. The controller has a first refrigeration circuit low-pressure suppression mode in which the controller reduces a flow rate of the second refrigerant circulating in the second refrigeration circuit and reduces an opening level of the first throttle such that pressure at a low pressure side of the first refrigeration circuit falls to or below a predetermined value. This configuration provides a heat pump device that prevents a rise in pressure at a low pressure side of a refrigeration cycle for hot-water supply.

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